AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. **(currently amended)** A method [[for]] of fabricating Surface Acoustic Wave (SAW) filter packages, the method comprising the ~~following~~ steps of:

preparing a plurality of SAW filter chips and a package sheet, wherein the package sheet has

an outline pattern of a predetermined width formed along outer peripheries of predetermined chip mounting areas where the SAW filter chips are to be mounted, and

circular anti-bur holes formed at corners of the chip mounting areas ~~to be mounted with the SAW filter chips~~;

mounting the SAW filter chips on the package sheet;

forming a protective layer on the SAW filter chips on the package sheet;

removing predetermined portions of the protective layer between the SAW filter chips to expose the outline pattern on the package sheet and predetermined portions of the package sheet between the SAW filter chips;

forming a metal shield layer on the SAW filter chips, the exposed portions of the package sheet and the outline pattern; and

cutting the package sheet along predetermined cutting lines ~~extended~~ extending through the anti-but holes between the SAW filter chips to form a plurality of SAW filter packages.

2. **(currently amended)** The method ~~for fabricating Surface Acoustic Wave filter~~

~~packages~~ as set forth in claim 1, wherein the outline pattern is formed on the package sheet with a predetermined length corresponding to the outer peripheries of the SAW filter chips.

3. **(currently amended)** The method ~~for fabricating Surface Acoustic Wave filter packages~~ as set forth in claim 1, wherein each of the anti-bur holes has a predetermined size to cover all adjacent corners of the corresponding chip mounting areas.

4. **(currently amended)** The method ~~for fabricating Surface Acoustic Wave filter packages~~ as set forth in claim 1, wherein the package sheet comprises at least two sheet layers.

5. **(currently amended)** The method ~~for fabricating Surface Acoustic Wave filter packages~~ as set forth in claim 4, wherein the anti-bur holes are formed in at least one sheet layer of the at least two sheet layers, the one sheet layer having a surface for mounting the SAW filter chips.

6. **(currently amended)** The method ~~for fabricating Surface Acoustic Wave filter packages~~ as set forth in claim 1, wherein the SAW filter chips are provided on undersides thereof with bumps for mounting the SAW filter chips.

7. **(currently amended)** The method ~~for fabricating Surface Acoustic Wave filter packages~~ as set forth in claim 1, wherein the protective layer comprises a photosensitive film.

8. **(currently amended)** The method ~~for fabricating Surface Acoustic Wave filter packages~~ as set forth in claim 7, wherein the step of removing predetermined portions of the protective layer is carried out by dry etching.

9. **(currently amended)** A package sheet for a Surface Acoustic Wave (SAW) filter package, said package sheet comprising:

an outline pattern formed along outer peripheries of predetermined chip mounting areas where ~~to be mounted with~~ a plurality of SAW filter chips are to be mounted, the outline pattern being adapted to contact ~~contacted with~~ a metal shield layer which is to be formed on the SAW filter chips and in a predetermined region of the package sheet; and

~~circular~~ anti-bur holes located at ~~covering~~ corners of the chip mounting areas ~~to be mounted with the SAW filter chips~~ and intersected by cutting lines along which ~~functioning as reference lines for cutting~~ the package sheet is to be cut into a plurality of SAW filter packages.

10. **(currently amended)** The package sheet ~~for a Surface Acoustic Wave filter package~~ as set forth in claim 9, wherein the outline pattern is formed [[in]] on the package sheet with a length corresponding to the outer peripheries of the SAW filter chips.

11. **(currently amended)** The package sheet ~~for a Surface Acoustic Wave filter package~~ as set forth in claim 9, wherein each of the anti-bur holes has a predetermined size to cover all adjacent corners of the corresponding chip mounting areas.

12. **(currently amended)** The package sheet ~~for a Surface Acoustic Wave filter package~~ as set forth in claim 9, wherein the package sheet comprises at least two sheet layers.

13. **(currently amended)** The package sheet ~~for a Surface Acoustic Wave filter package~~ as set forth in claim 12, wherein the anti-bur holes are formed in at least one sheet layer of the at least two sheet layers, the one sheet layer having a surface for mounting the SAW filter chips.

14. **(currently amended)** A Surface Acoustic Wave filter package fabricated according to the method as set forth in claim 1.

15. **(currently amended)** A Surface Acoustic Wave filter package fabricated using the

package sheet as set forth in claim 9.

16. **(new)** The SAW package as set forth in claim 15, comprising:

a substrate defined by a piece of said package sheet and having one of said chip mounting areas;

a ground pattern defined by the outline pattern surrounding the chip mounting area on said substrate;

a SAW filter chip mounted in the chip mounting area on said substrate; and

a metal shield layer formed on the SAW filter chip and in contact with the ground pattern;

wherein the ground pattern has at least a concave cut-out defined by a peripheral edge of one of the anti-bur holes.

17. **(new)** The package sheet as set forth in claim 9, wherein the outline pattern has multiple concave cut-outs defined by peripheral edges of the anti-bur holes.

18. **(new)** The package sheet as set forth in claim 9, wherein

the outline pattern comprises first conductive lines surrounding the respective chip mounting areas, and second conductive lines extending between the chip mounting areas and connecting the first conductive lines; and

a number of said anti-bur holes are located on said second conductive lines and define in said second conductive lines a plurality of cut-outs.

19. **(new)** The method as set forth in claim 1, wherein the outline pattern has multiple concave cut-outs defined by peripheral edges of the anti-bur holes.

20. **(new)** A method of fabricating Surface Acoustic Wave (SAW) filter packages, the method comprising the steps of:

preparing a plurality of SAW filter chips and a package sheet, wherein the package sheet has

an outline pattern of a predetermined width formed along outer peripheries of predetermined chip mounting areas where the SAW filter chips are to be mounted, and

anti-bur holes formed at corners of the chip mounting areas;

mounting the SAW filter chips on the package sheet;

forming a protective layer on the SAW filter chips on the package sheet;

removing predetermined portions of the protective layer between the SAW filter chips to expose the outline pattern on the package sheet and predetermined portions of the package sheet between the SAW filter chips;

forming a metal shield layer on the SAW filter chips, the exposed portions of the package sheet and the outline pattern; and

cutting the package sheet along predetermined cutting lines extending through the anti-but holes between the SAW filter chips to form a plurality of SAW filter packages.